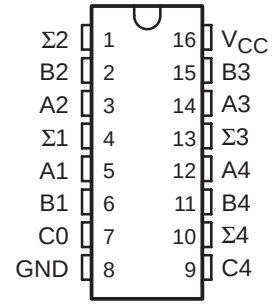
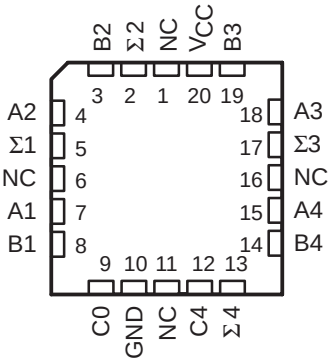
- **Full-Carry Look-Ahead Across the Four Bits**
- **Systems Achieve Partial Look-Ahead Performance With the Economy of Ripple Carry**
- **Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs**

SN54F283 . . . J PACKAGE
SN74F283 . . . D OR N PACKAGE
(TOP VIEW)



SN54F283 . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

description

The ′F283 is a full adder that performs the addition of two 4-bit binary words. The sum (Σ) outputs are provided for each bit and the resultant carry (C4) output is obtained from the fourth bit.

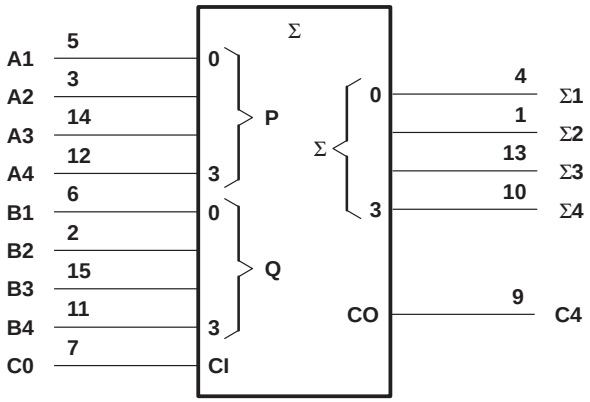
The device features full internal look-ahead across all four bits generating the carry term C4 in typically 5.7 ns. This capability provides the system designer with partial look-ahead performance at the economy and reduced package count of a ripple-carry implementation.

The adder logic, including the carry, is implemented in its true form. End-around carry can be accomplished without the need for logic or level inversion.

The ′F283 can be used with either all-active-high (positive logic) or all-active-low (negative logic) operands.

The SN54F283 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74F283 is characterized for operation from 0°C to 70°C.

logic symbol†

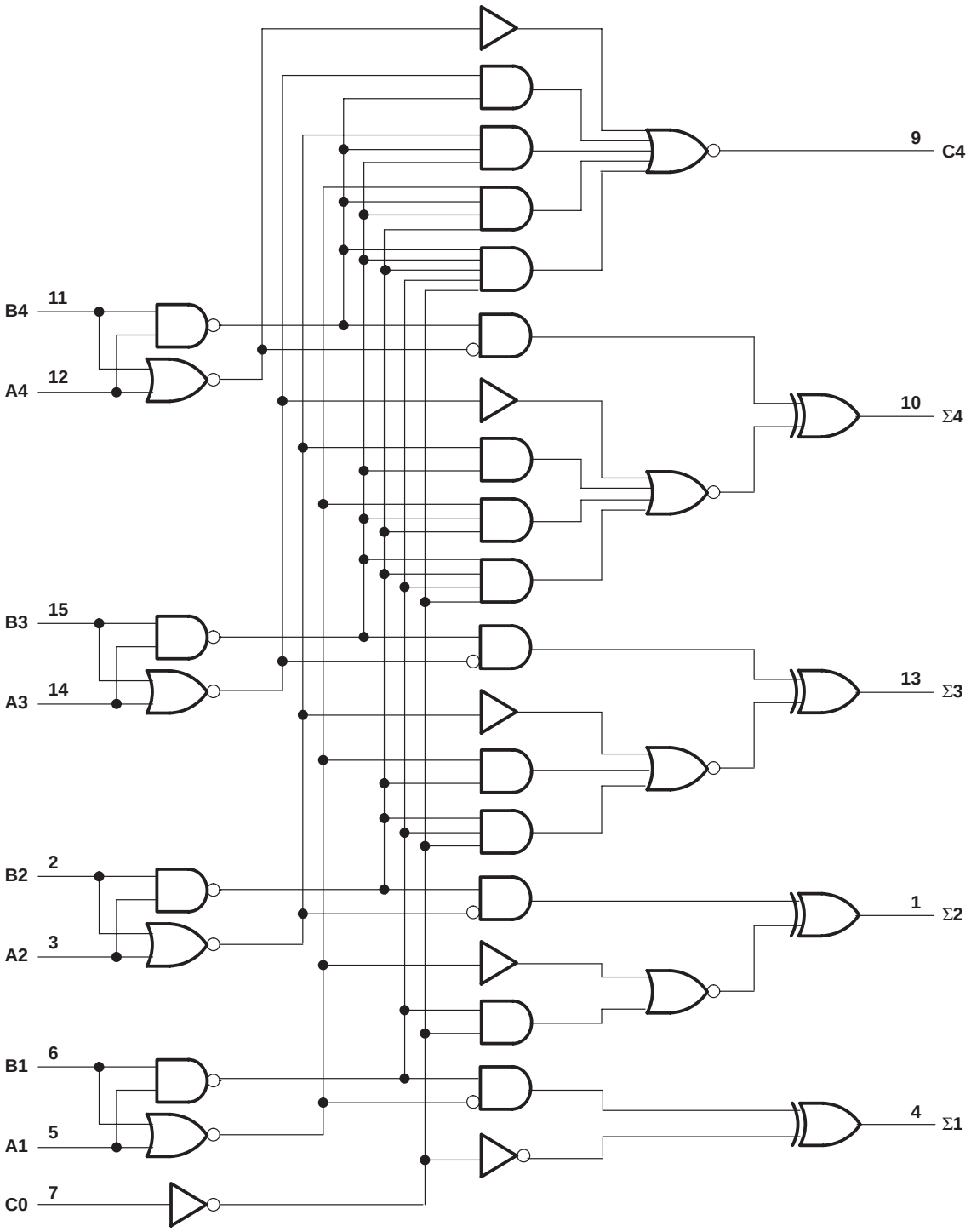


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

FUNCTION TABLE

INPUTS				OUTPUTS					
				WHEN C0 = L			WHEN C0 = H		
				WHEN C2 = L			WHEN C2 = H		
A1	B1	A2	B2	Σ1	Σ2	C2	Σ1	Σ2	C2
A3	B3	A4	B4	Σ3	Σ4	C4	Σ3	Σ4	C4
L	L	L	L	L	L	L	H	L	L
H	L	L	L	H	L	L	L	H	L
L	H	L	L	H	L	L	L	H	L
H	H	L	L	L	H	L	H	H	L
L	L	H	L	L	H	L	H	H	L
H	L	H	L	H	H	L	L	L	H
L	H	H	L	H	H	L	L	L	H
H	H	H	L	L	L	H	H	L	H
L	L	L	H	L	H	L	H	H	L
H	L	L	H	H	H	L	L	L	H
L	H	L	H	H	H	L	L	L	H
H	H	L	H	L	L	H	H	L	H
L	L	H	H	L	L	H	H	L	H
H	L	H	H	H	L	H	L	H	H
L	H	H	H	H	L	H	L	H	H
H	H	H	H	L	H	H	H	H	H

NOTE: Input conditions at A1, B1, A2, B2, and C0 are used to determine outputs Σ1 and Σ2 and the value of the internal carry C2. The values at C2, A3, B3, A4, and B4 are then used to determine outputs Σ3, Σ4, and C4.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range (see Note 1) . . . . . −1.2 V to 7 V
Input current range . . . . . −30 mA to 5 mA
Voltage range applied to any output in the high state . . . . . −0.5 V to V_{CC}
Current into any output in the low state . . . . . 40 mA
Operating free-air temperature range: SN54F283 . . . . . −55°C to 125°C
SN74F283 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F283			SN74F283			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			−18			−18	mA
I_{OH}	High-level output current			− 1			− 1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54F283			SN74F283			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}		V_{CC} = 4.5 V	I_{OH} = − 1 mA	2.5	3.4		2.5	3.4		V
		V_{CC} = 4.75 V,	I_{OH} = − 1 mA				2.7			
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 20 mA		0.3	0.5		0.3	0.5	V
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	Any A or B	V_{CC} = 5.5 V,	V_I = 0.5 V			− 1.2			− 1.2	mA
	C0					− 0.6			− 0.6	
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0	−60		−150	−60		−150	mA
I_{CC}		V_{CC} = 5.5 V,	V_I = 4.5 V		36	55		36	55	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R_L = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX§				UNIT
			′F283			SN54F283		SN74F283		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	C0	Σ	2.7	6.6	9.5	2.7	14	2.7	10.5	ns
t_{PHL}			3.2	6.6	9.5	3.2	14	3.2	10.5	
t_{PLH}	A or B	Σ	3.2	6.6	9.5	3.2	14	3.2	10.5	ns
t_{PHL}			2.7	6.6	9.5	2.7	14	2.7	10.5	
t_{PLH}	C0	C4	2.7	5.3	7.5	2.7	10.5	2.7	8.5	ns
t_{PHL}			2.2	5	7	2.2	10	2.2	8	
t_{PLH}	A or B	C4	2.7	5.3	7.5	2.7	10.5	2.7	8.5	ns
t_{PHL}			2.2	4.9	7	2.2	10	2.2	8	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
NOTE 2: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9758701Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
5962-9758701QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	-55 to 125	5962-9758701QEA SNJ54F283J	Samples
5962-9758701QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	-55 to 125	5962-9758701QEA SNJ54F283J	Samples
5962-9758701QFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
5962-9758701QFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/34201B2A	Samples
JM38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/34201B2A	Samples
JM38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BEA	Samples
JM38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BEA	Samples
JM38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BFA	Samples
JM38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BFA	Samples
M38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/34201B2A	Samples
M38510/34201B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/34201B2A	Samples
M38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BEA	Samples
M38510/34201BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BEA	Samples
M38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/34201BFA	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
M38510/34201BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34201BFA	Samples
SN54F283J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54F283J	Samples
SN54F283J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54F283J	Samples
SN74F283D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F283	Samples
SN74F283N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SN74F283N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SN74F283N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74F283N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74F283NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SN74F283NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F283N	Samples
SN74F283NSR	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70	74F283	
SN74F283NSR	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70	74F283	
SN74F283NSRE4	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		
SN74F283NSRE4	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		
SN74F283NSRG4	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		
SN74F283NSRG4	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI	0 to 70		
SNJ54F283FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
SNJ54F283FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-9758701Q2A SNJ54F 283FK	Samples
SNJ54F283J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9758701QEA SNJ54F283J	Samples
SNJ54F283J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9758701QEA SNJ54F283J	Samples
SNJ54F283W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54F283W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN54F283, SN74F283 :

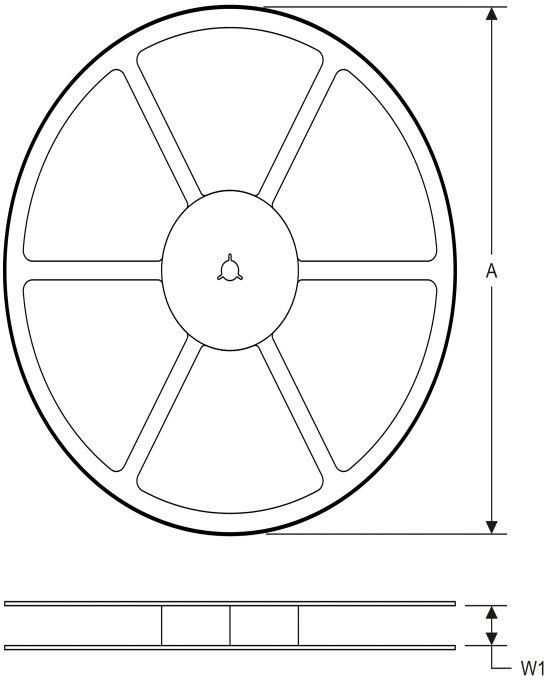
- Catalog: SN74F283
- Military: SN54F283

NOTE: Qualified Version Definitions:

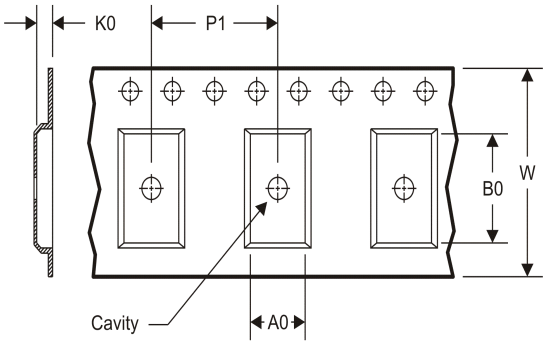
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



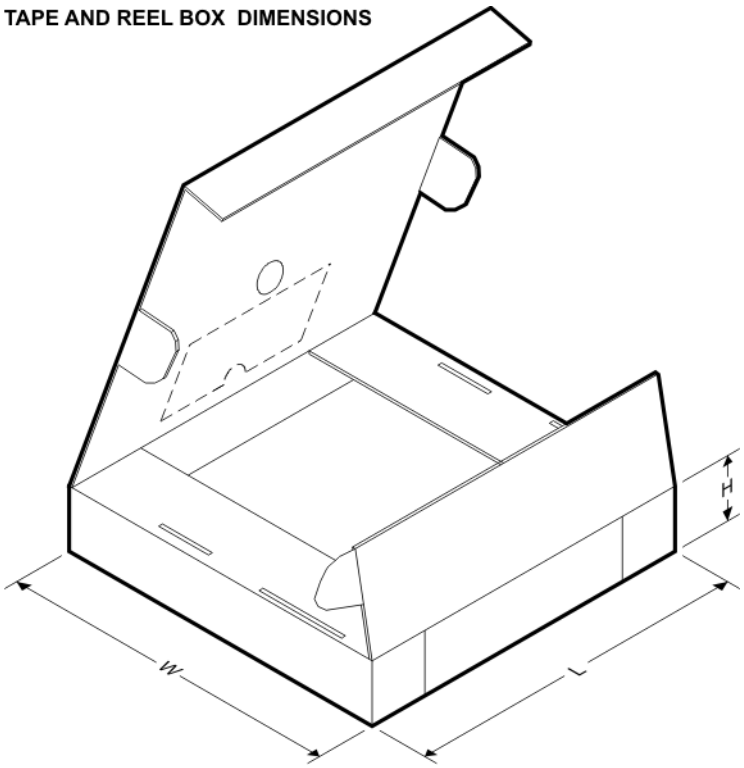
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F283DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



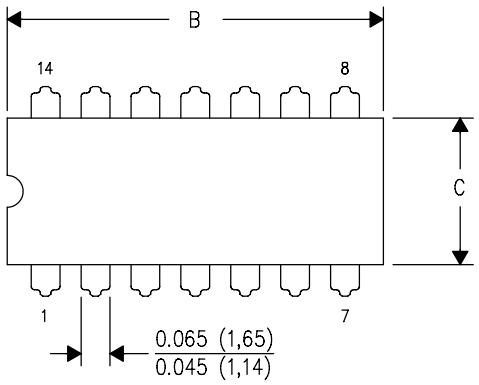
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F283DR	SOIC	D	16	2500	333.2	345.9	28.6

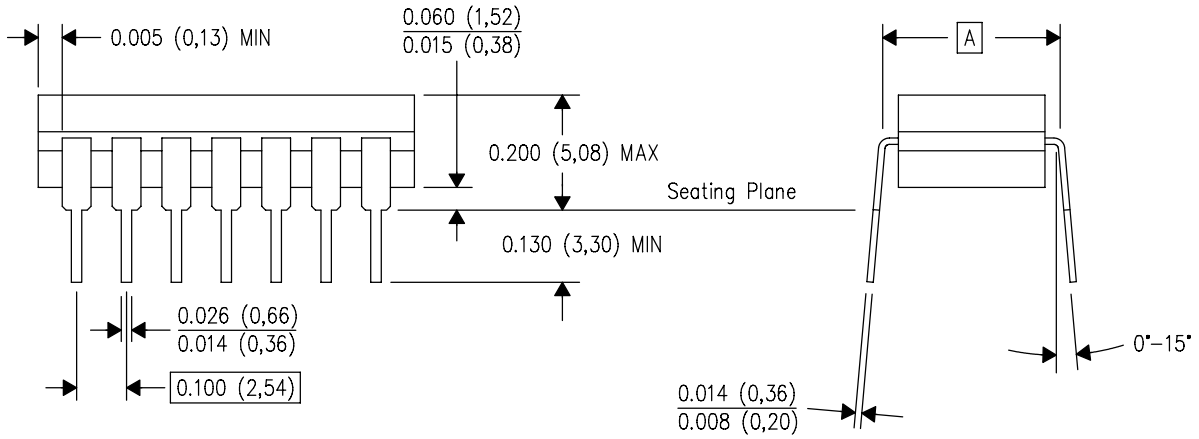
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



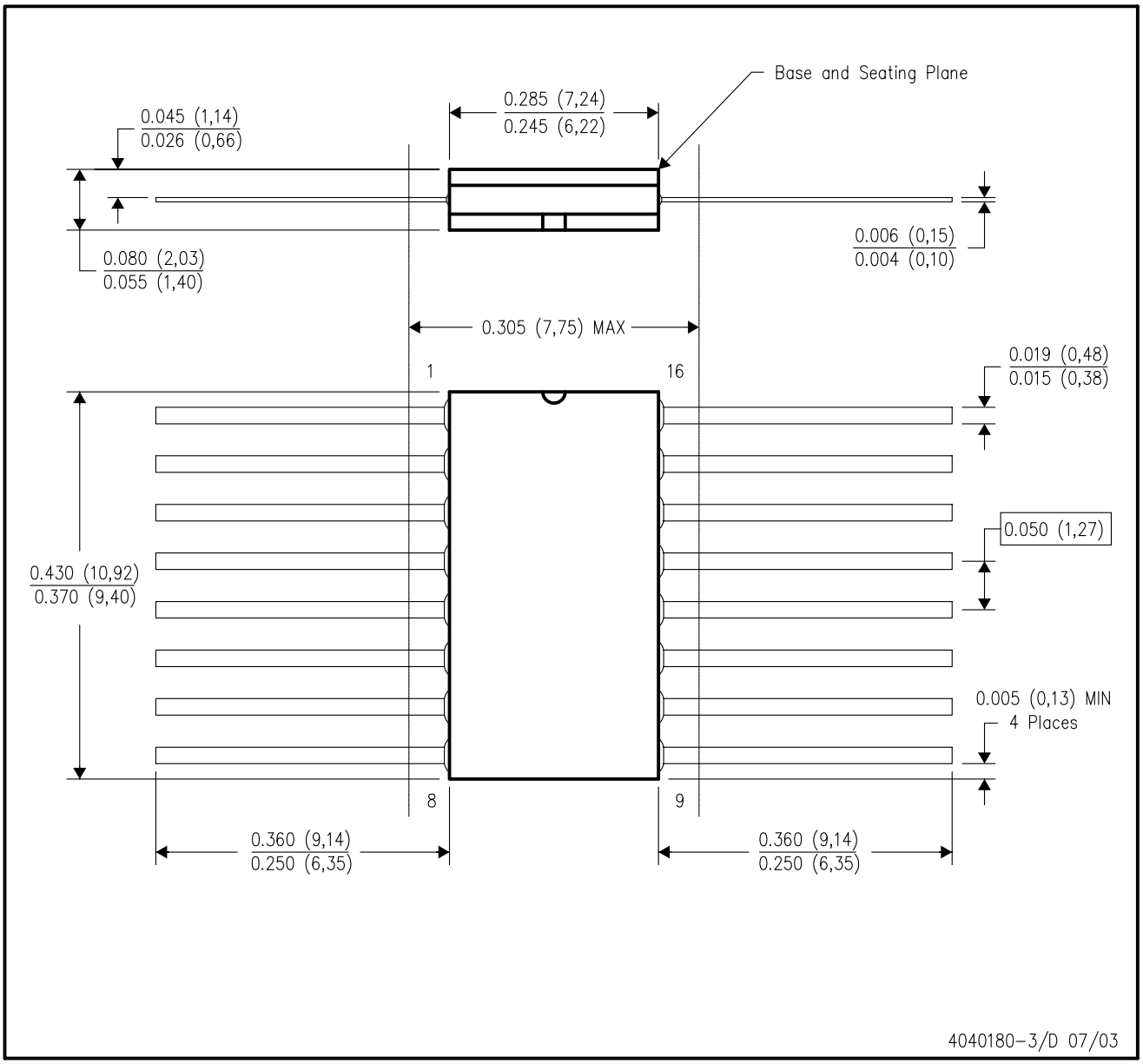
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

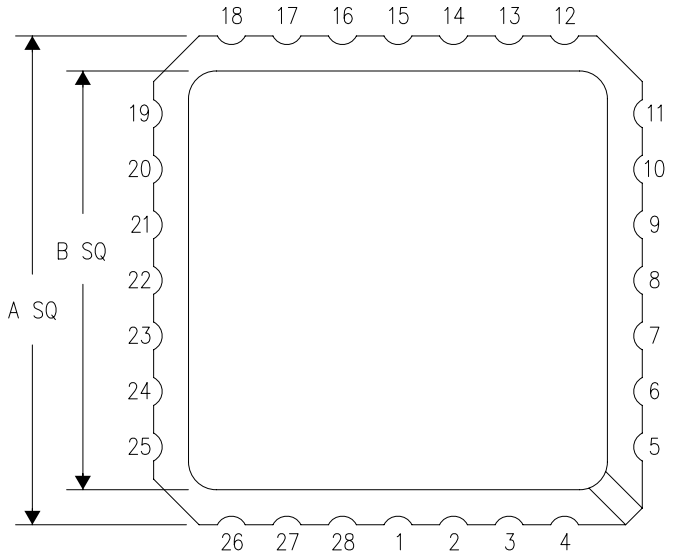
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



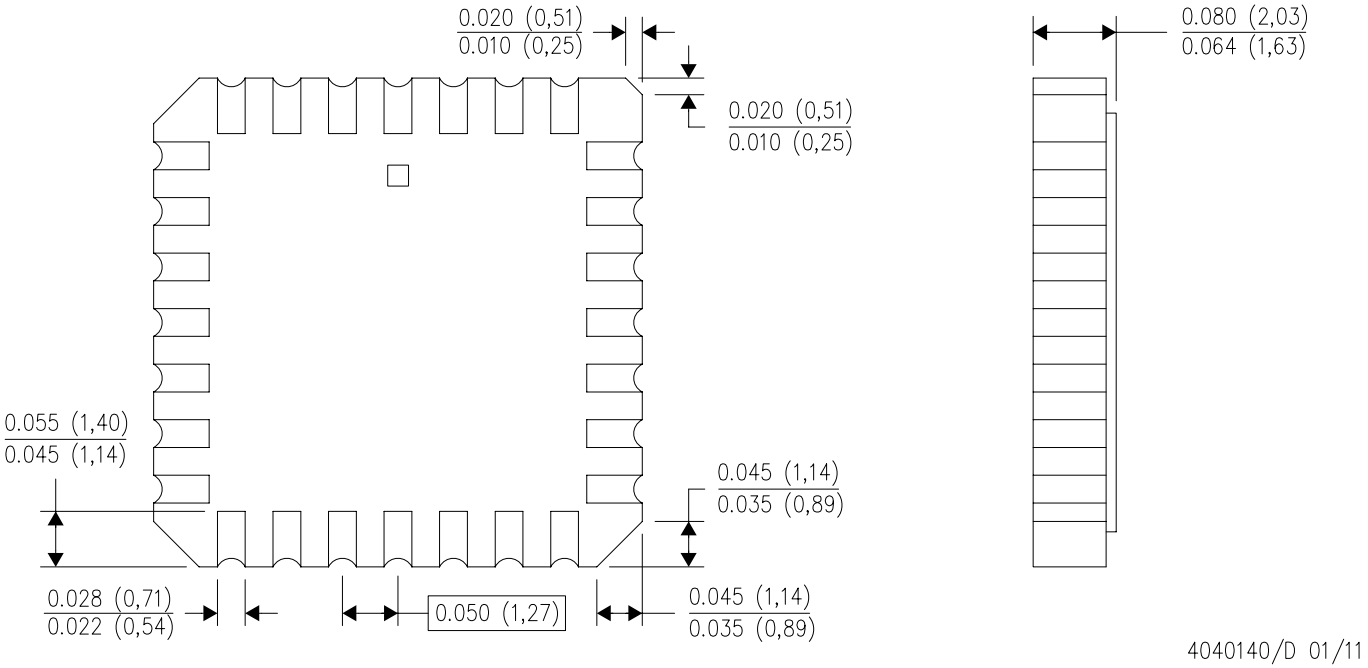
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F16 and JEDEC MO–092AC

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



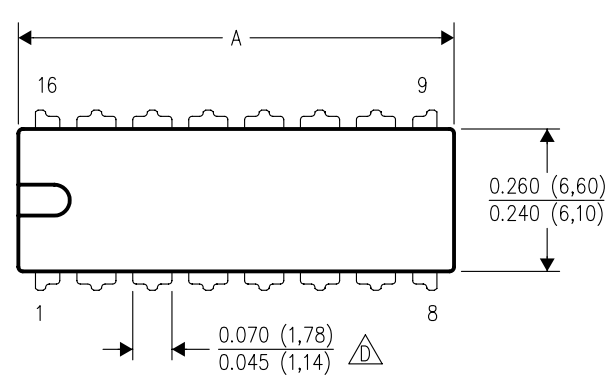
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

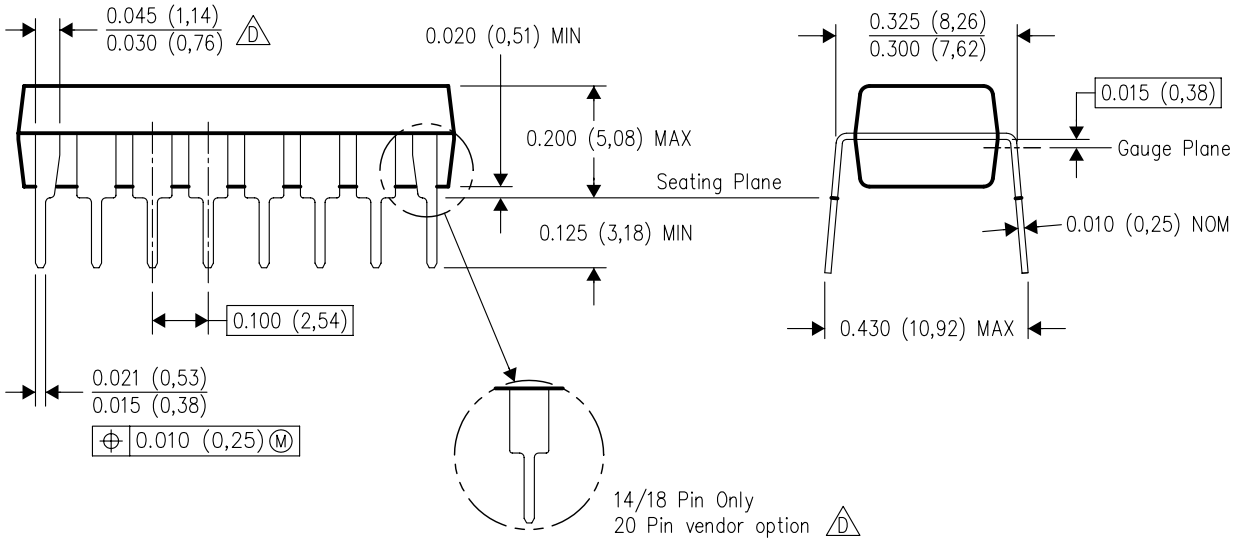
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



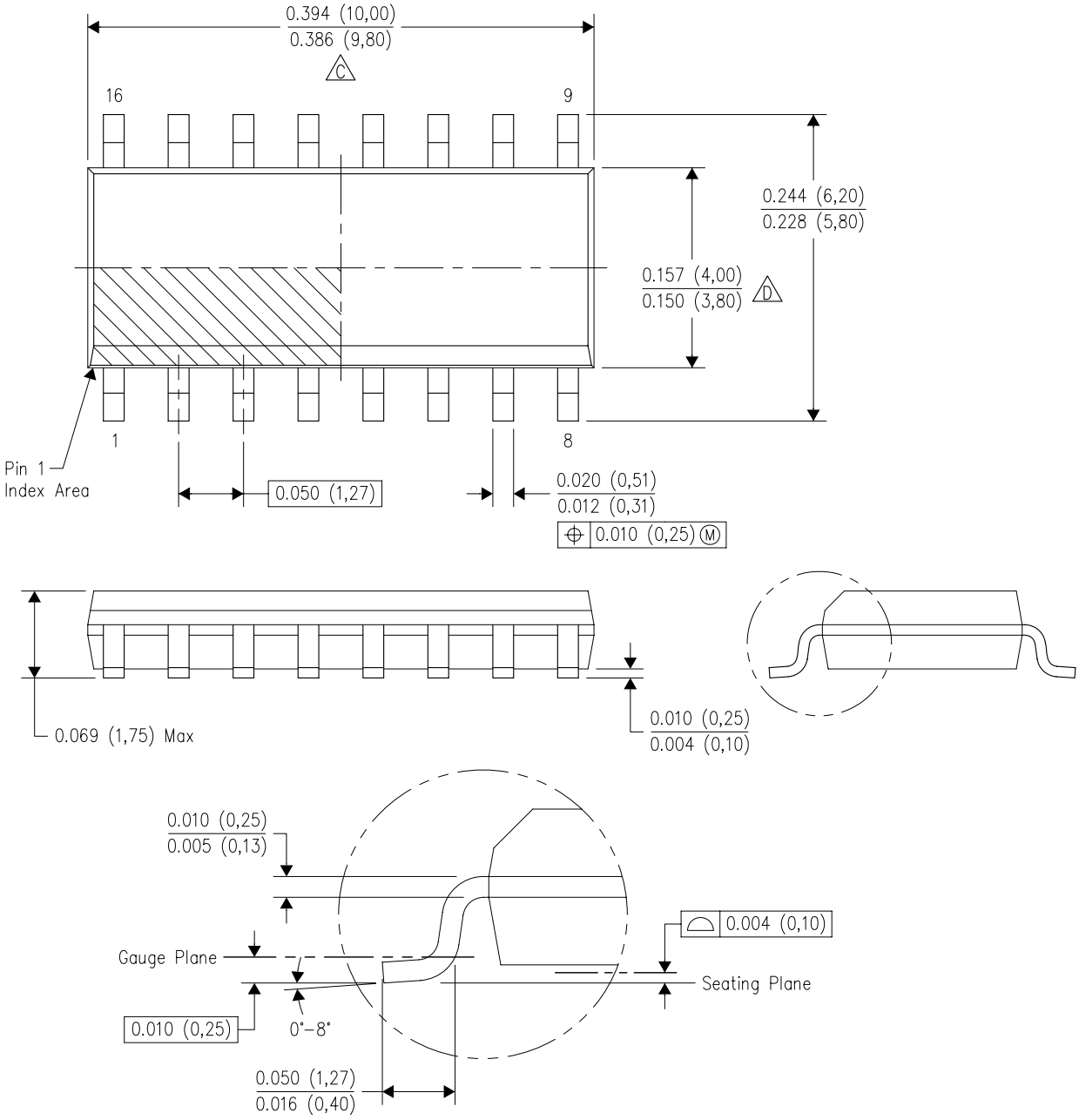
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

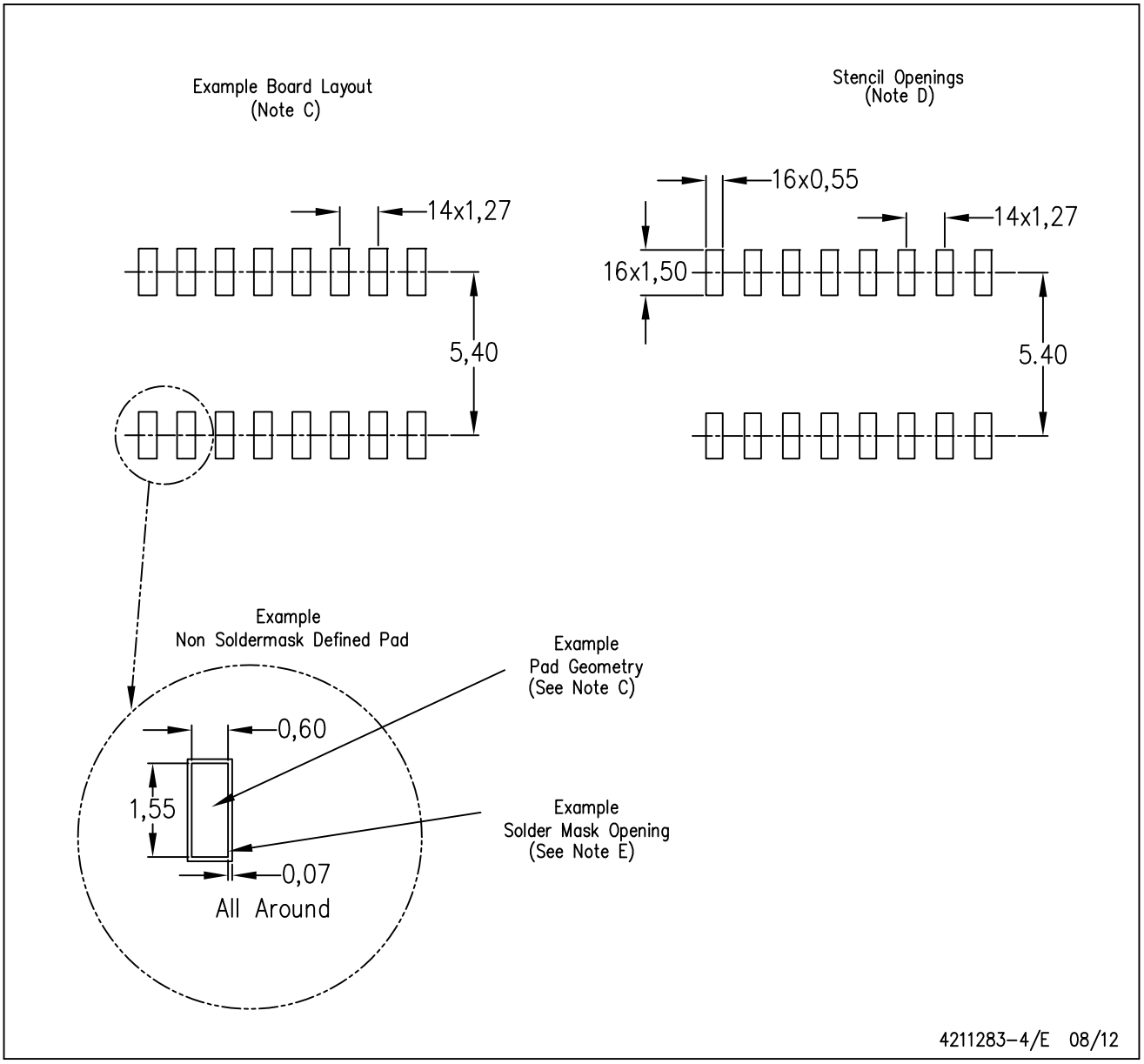
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

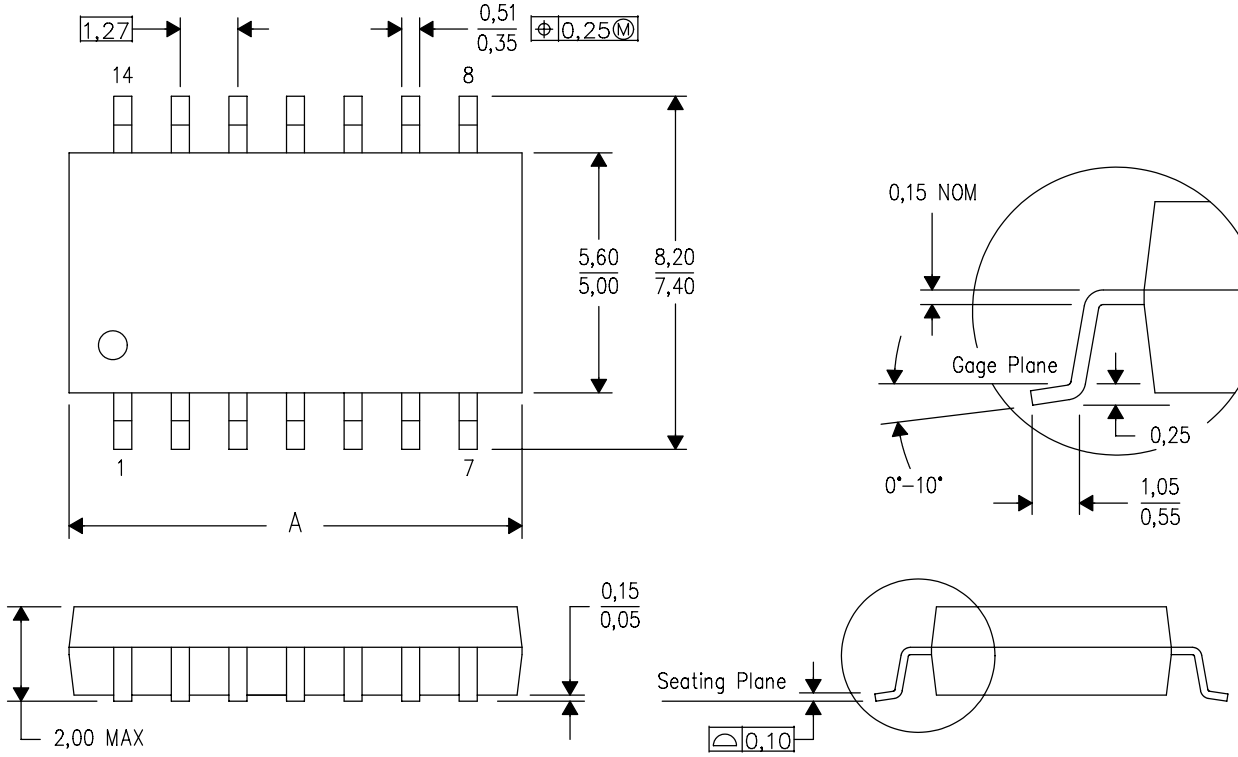


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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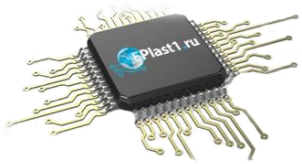
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